



US00D323061S

United States Patent [19]**Takahashi et al.**[11] **Patent Number: Des. 323,061**[45] **Date of Patent: ** Jan. 14, 1992**[54] **PACKAGE FOR ELECTRONIC PARTS OR THE LIKE**[75] **Inventors: Tetsuo Takahashi; Kuniaki Takahashi; Koji Kudo, all of Tokyo, Japan**[73] **Assignee: TDK Corporation, Tokyo, Japan**[**] **Term: 14 Years**[21] **Appl. No.: 423,104**[22] **Filed: Oct. 18, 1989**[30] **Foreign Application Priority Data**

Apr. 18, 1989 [JP] Japan 1-14284

[52] **U.S. Cl. D3/35**[58] **Field of Search D3/35, 30.1; D9/341, D9/428; 221/197, 287; 206/533, 538, 539, 328, 334, 313; D14/120-123**[56] **References Cited****U.S. PATENT DOCUMENTS**D. 273,805 5/1984 Filhol D9/341 X
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4,811,998 3/1989 Rankin 206/372 X*Primary Examiner*—Bernard Ansher*Assistant Examiner*—Prabhakar Deshmukh*Attorney, Agent, or Firm*—Helfgott & Karas[57] **CLAIM**

The ornamental design for a package for electronic parts or the like, as shown and described.

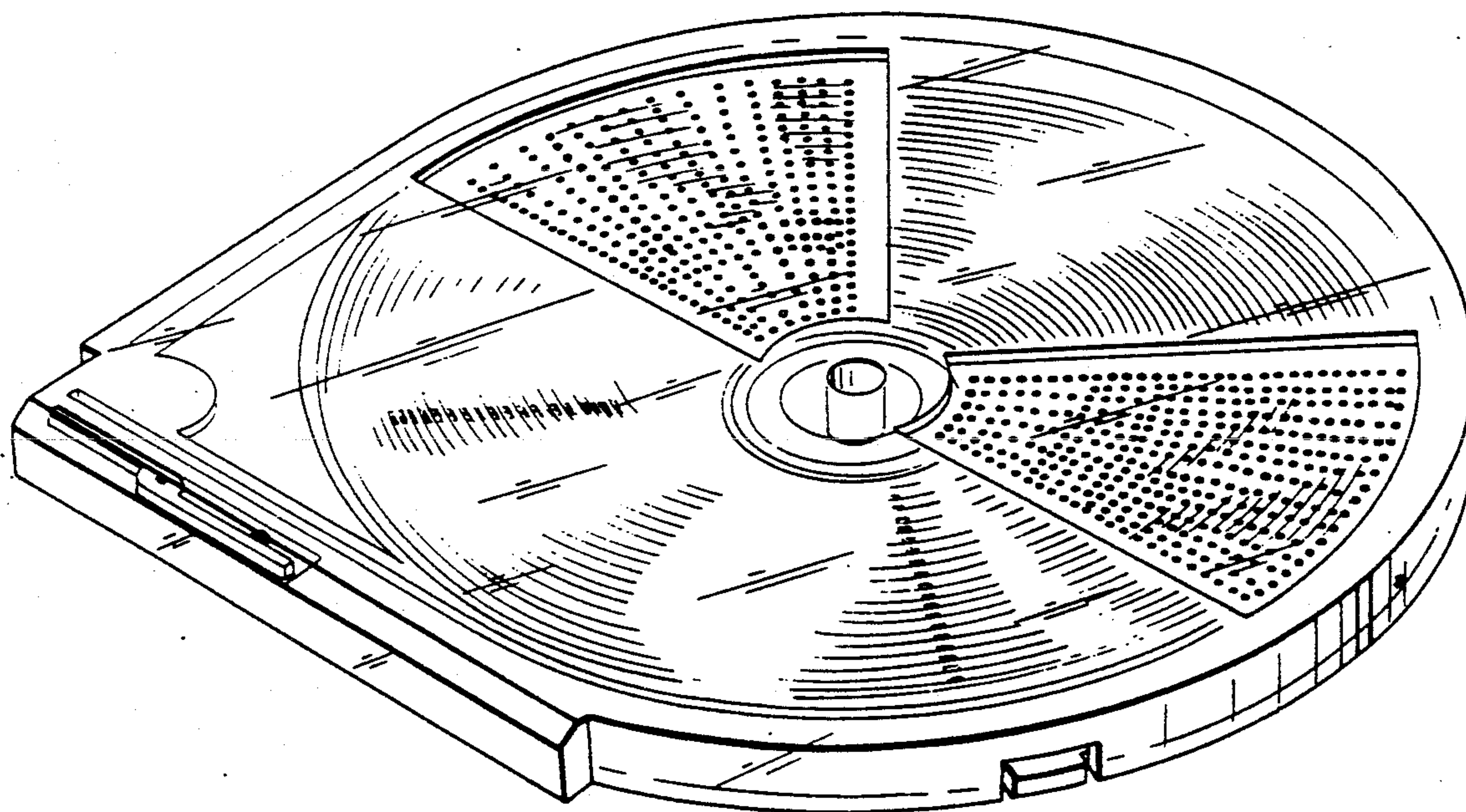
DESCRIPTIONFIG. 1 is a front perspective view of a package for electronic parts or the like showing our new design;
FIG. 2 is a rear perspective view thereof;
FIG. 3 is a front elevation thereof;
FIG. 4 is a rear elevation thereof;
FIG. 5 is a top plan view thereof;
FIG. 6 is a bottom plan view thereof;
FIG. 7 is a left side elevation thereof; and
FIG. 8 is a right side elevation thereof.

FIG. 1

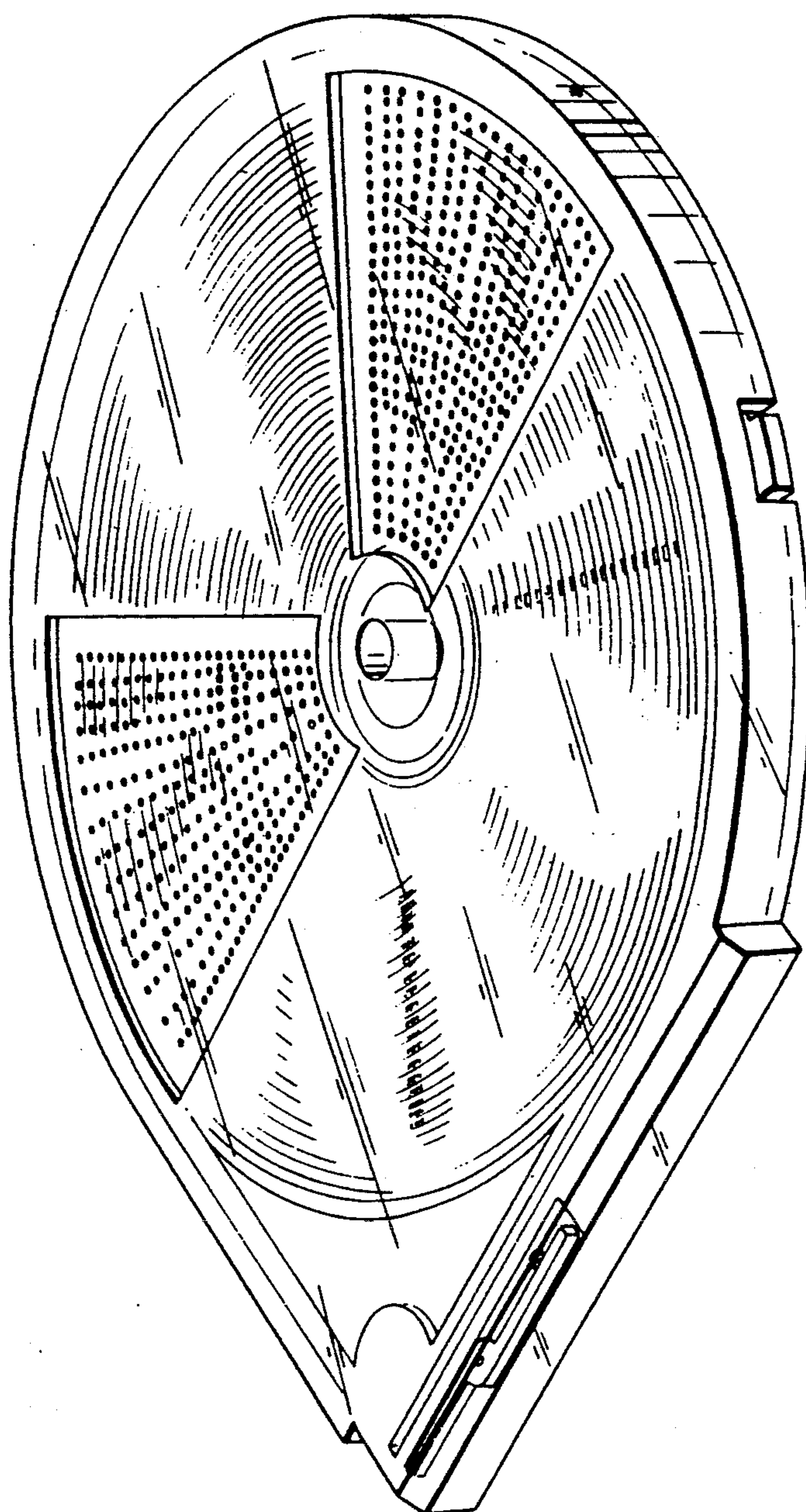


FIG. 2

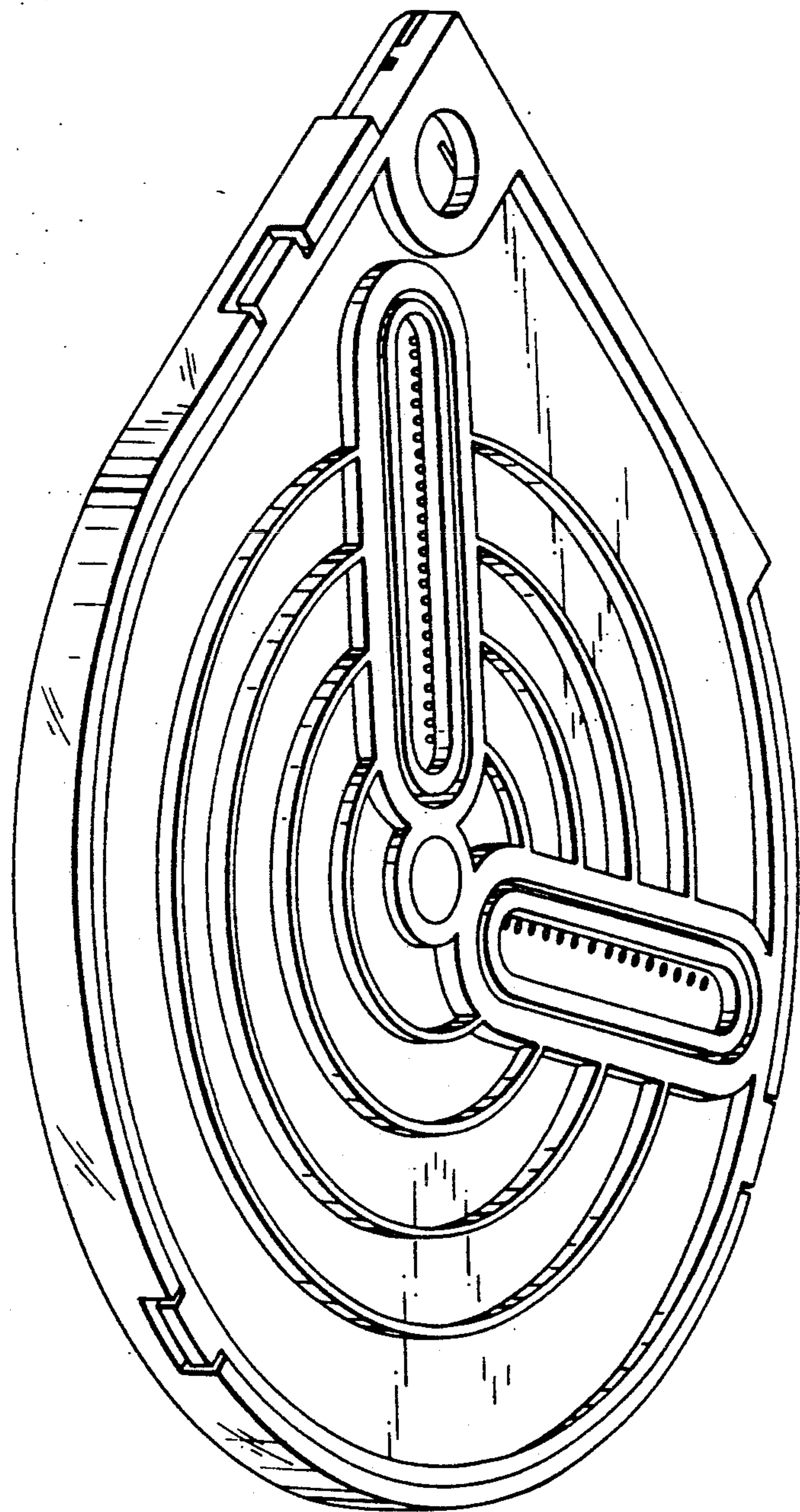


FIG. 3

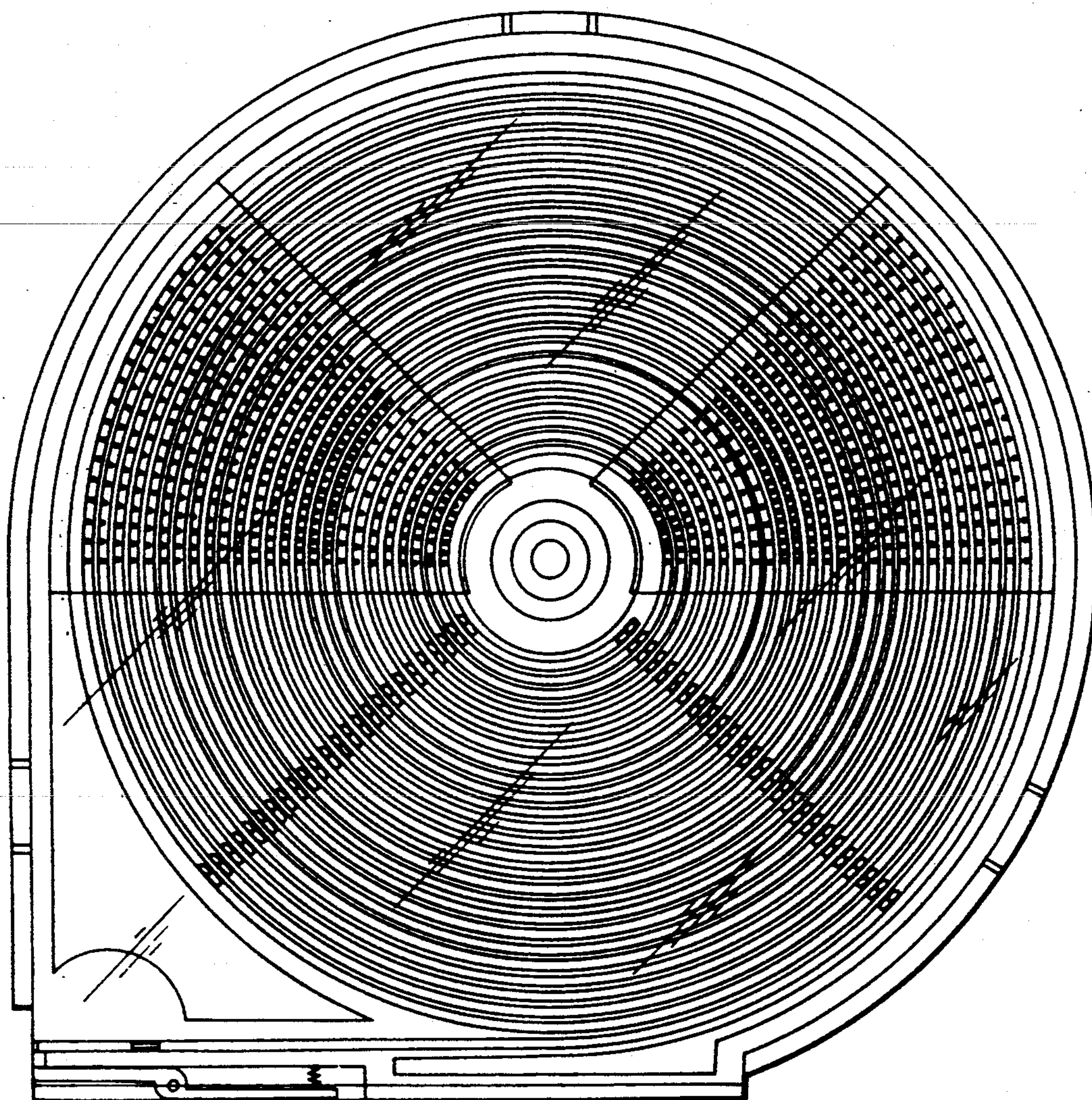


FIG. 4

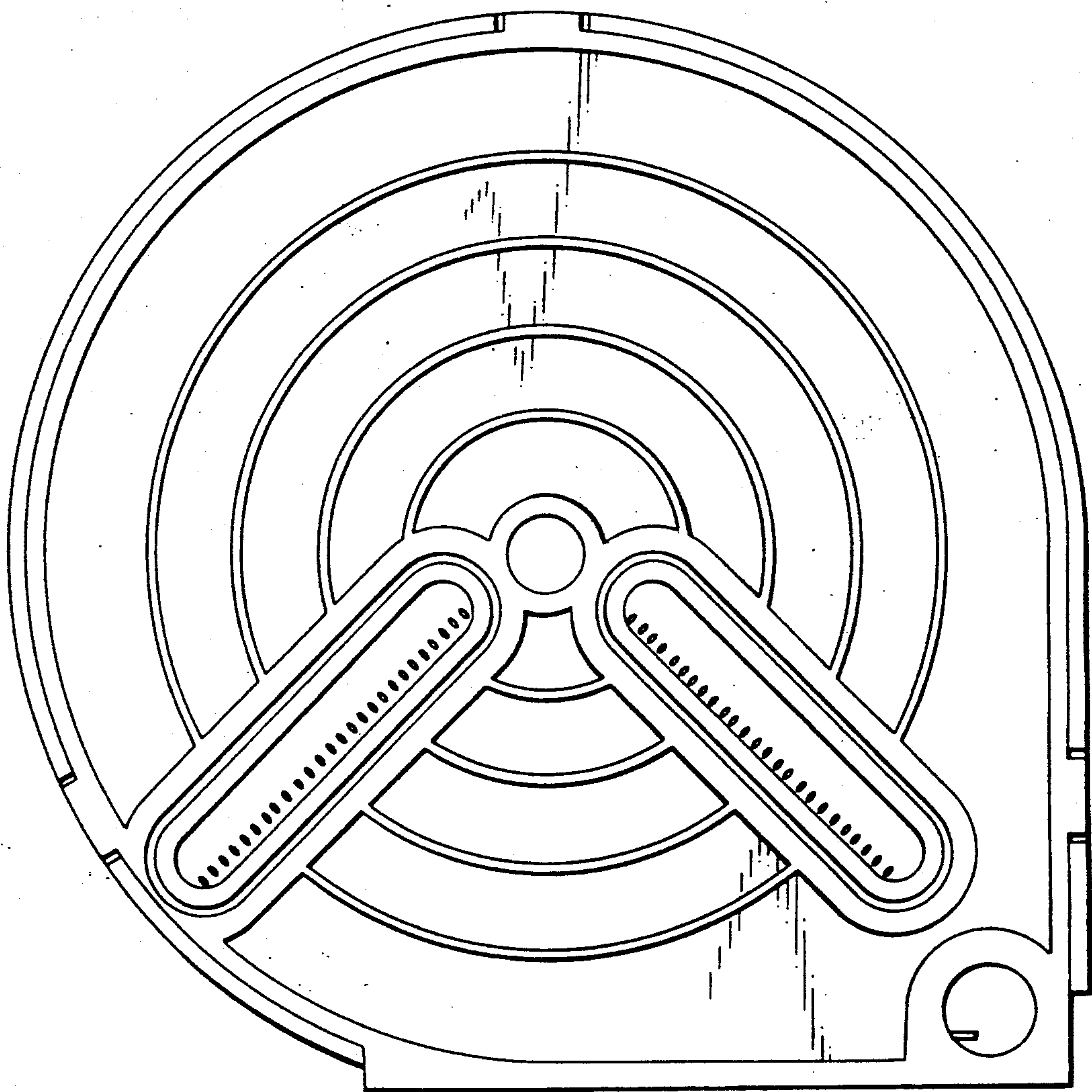


FIG. 5



FIG. 6

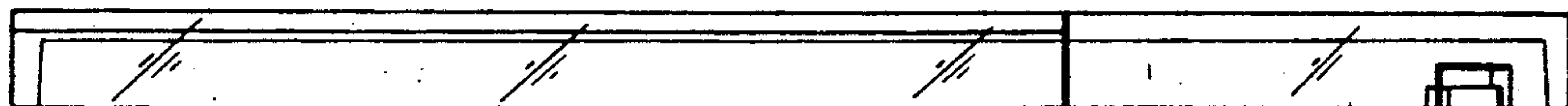


FIG. 7

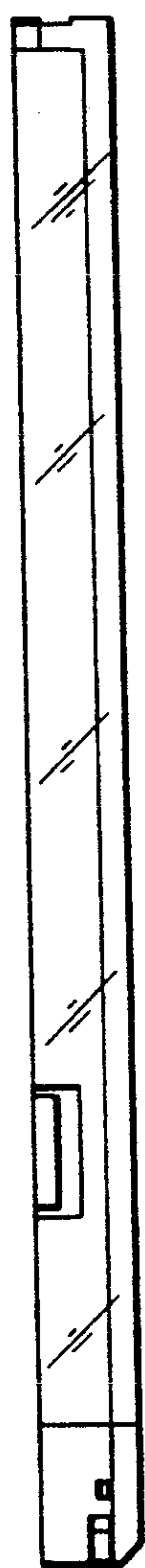


FIG. 8

